



Attorney Docket No. 5347-219

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Engbrecht et al.  
Application Serial No.: 10/826,564  
Filed: April 16, 2004  
For: METHODS OF FORMING BORON CARBO-NITRIDE LAYERS FOR  
INTEGRATED CIRCUIT DEVICES

Confirmation No.: 2107  
Group Art Unit: 2811  
Examiner: To Be Assigned

Date: August 20, 2004

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. § 1.97(c)  
FOR APPLICATION FILED AFTER JUNE 30, 2003**

Sir:

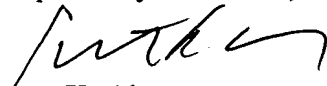
Attached is a list of documents on Form PTO-1449, together with a copy of any listed foreign patent document and/or non-patent literature. A copy of any listed U.S. patent and/or U.S. patent application publication is not provided herewith in accordance with the waiver by the U.S. Patent and Trademark Office of requirements under 37 C.F.R. § 1.98(a)(2)(i) for all U.S. national patent applications filed after June 30, 2003 and for all international

It is requested that these documents be considered by the Examiner and officially made of record in accordance with the provisions of 37 C.F.R. § 1.56 and Section 609 of the MPEP.

No fee is believed due. However, the Commissioner is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-0220.

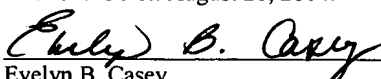
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**Certificate of Mailing under 37 CFR 1.8 [or under 37 CFR 1.10 -see above]**

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on August 20, 2004.

  
Evelyn B. Casey

AUG 23 2004

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Application Number	10/826,564
Filing Date	April 16, 2004
First Named Inventor	Engbrecht et al.
Group Art Unit	2811
Examiner Name	To be assigned
Attorney Docket Number	5347-219

[illegible][illegible]

OTHER NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T
	6.	Fayolle et al.; "Integration of Cu/SiOC in Dual Damascene interconnect for 0.1 $\mu$ m technology using a new SiC material as dielectric barrier" 2002 <i>IEEE International Interconnect Technology Conference</i> , Burlingame, CA 39-41 (2002).	
	7.	Gelatos et al.; "The Properties of a Plasma Deposited Candidate Insulator for Future Multilevel Interconnects Technology" <i>Mat. Res. Soc. Symp.</i> <b>250</b> 347-354 (1992).	
	8.	Levy et al. "Evaluation of LPCVD Boron Nitride as a Low Dielectric Constant Material" <i>Mat. Res. Soc. Symp.</i> <b>427</b> 469-478 (1996).	
	9.	Martin et al.; "Integration of SiCN as a Low $\kappa$ Etch Stop and Cu Passivation in a High Performance Cu/Low $\kappa$ Interconnect" 2002 <i>IEEE International Interconnect Technology Conference</i> , Burlingame, CA 4244 (2002).	
	10.	Nguyen et al.; "Plasma-Assisted Chemical Vapor Deposition and Characterization of Boron Nitride Films" <i>J. Electrochem. Soc.</i> , <b>141</b> :6 1633-1638 (1994).	
	11.	Sugino et al.; "Dielectric constant of boron carbon nitride films synthesized by plasma-assisted chemical-vapor deposition" <i>Applied Physics Letters</i> <b>80</b> :4 649-651 (2002).	

Date Considered